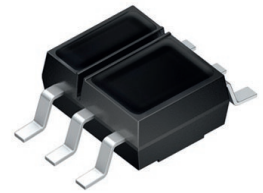


# SFH 9206

## Reflective Interrupter



### Applications

- Industrial Automation (Machine Controls, Light Barriers, Vision Controls)

### Features:

- Qualifications: The product qualification test plan is based on the guidelines of AEC-Q101-REV-C, Stress Test Qualification for Automotive Grade Discrete Semiconductors.
- ESD: 2 kV acc. to ANSI/ESDA/JEDEC JS-001 (HBM, Class 2)
- 940nm emitter in combination with a silicon NPN phototransistor
- Optimal operating distance 1 mm to 5 mm
- Daylight cut-off filter
- Emitter and detector electrically isolated
- Soldering Methode: IR Reflow Soldering
- Product complies to MSL Level 4

### Ordering Information

Type	Ordering Code
SFH 9206	Q65111A3179
SFH 9206-5/6	Q65111A3177
SFH 9206-6/7	Q65111A3178

## Maximum Ratings

$T_A = 25\text{ °C}$

Parameter	Symbol		Values
<b>Emitter</b>			
Reverse voltage	$V_R$	max.	5 V
Forward current	$I_F$	max.	50 mA
Surge current $t_p \leq 10\ \mu\text{s}$ , $D = 0$	$I_{FSM}$	max.	0.7 A
Power consumption	$P_{tot}$	max.	100 mW
Thermal resistance junction – ambient <sup>1)</sup>	$R_{thJA}$	max.	495 K/W
<b>Detector</b>			
Emitter-collector voltage	$V_{EC}$	max.	7 V
Collector current	$I_C$	max.	10 mA
Collector-emitter voltage	$V_{CE}$	max.	16 V
Collector-emitter voltage $t \leq 2\ \text{min}$	$V_{CE}$	max.	30 V
Total Power dissipation	$P_{tot}$	max.	100 mW
Thermal resistance junction – ambient <sup>1)</sup>	$R_{thJA}$	max.	495 K/W
<b>Interrupter</b>			
Operating temperature	$T_{op}$	min.	-40 °C
		max.	100 °C
Storage temperature	$T_{stg}$	min.	-40 °C
		max.	100 °C
Ambient temperature range	$T_A$	min.	-40 °C
		max.	100 °C
Total power dissipation	$P_{tot}$	max.	150 mW
Electrostatic discharge	$V_{EDS}$	max.	2 kV

## Characteristics

$T_A = 25\text{ °C}$

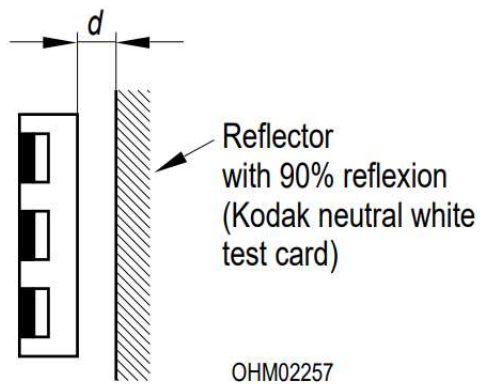
Parameter	Symbol		Values
<b>Emitter</b>			
Peak wavelength IF = 50 mA, $t_p = 20\text{ ms}$	$\lambda_{\text{peak}}$	typ.	950 nm
Forward voltage IF = 50 mA, $t_p = 20\text{ ms}$	VF	typ. max.	1.45 V 1.8 V
Reverse current VR = 5 V	IR		not designed for reverse operation
<b>Detector</b>			
Dark current VCE = 16 V, E = 0	ICE0	typ. max.	1 nA 50 nA
Capacitance VCE = 0 V, f = 1 MHz, E = 0	CCE	typ.	5 pF
Photocurrent (ambient light sensitivity) VCE = 5 V, EV = 1000 lx	IPCE	typ.	1 mA
<b>Interrupter</b>			
Collector-emitter current Kodak neutral white testcard with 90% reflection; IF = 10 mA, VCE = 5 V, d = 1 mm	IPCE	min. typ. max.	160 $\mu\text{A}$ 600 $\mu\text{A}$ 2000 $\mu\text{A}$
Collector-emitter saturation voltage Kodak neutral white testcard with 90% reflection; IF = 10 mA, IC = 55 $\mu\text{A}$ , d = 1 mm	VCEsat	typ. max.	200 mV 600 mV
<b>Switching Times</b>			
Turn-on time 2) VCC = 5 V, IC = 100 $\mu\text{A}$ , RL = 1 k $\Omega$	ton	typ.	40 $\mu\text{s}$
Turn-off time 2) VCC = 5 V, IC = 100 $\mu\text{A}$ , RL = 1 k $\Omega$	toff	typ.	45 $\mu\text{s}$
Rise time 2) VCC = 5 V, IC = 100 $\mu\text{A}$ , RL = 1 k $\Omega$	tr	typ.	30 $\mu\text{s}$
Fall time 2) VCC = 5 V, IC = 100 $\mu\text{A}$ , RL = 1 k $\Omega$	tf	typ.	40 $\mu\text{s}$

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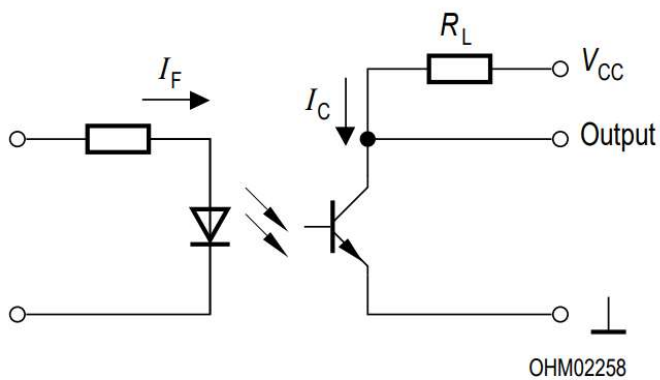
**Photocurrent Groups** $T_A = 25\text{ °C}$ 

Group	Photocurrent	Photocurrent
	$V_{CE} = 5\text{ V}; \lambda = 940\text{ nm}; E_e = 0.1\text{ mW/cm}^2$ min. $I_{PCE}$	$V_{CE} = 5\text{ V}; \lambda = 940\text{ nm}; E_e = 0.1\text{ mW/cm}^2$ max. $I_{PCE}$
4	180 $\mu\text{A}$	280 $\mu\text{A}$
5	280 $\mu\text{A}$	450 $\mu\text{A}$
6	450 $\mu\text{A}$	710 $\mu\text{A}$
7	710 $\mu\text{A}$	1120 $\mu\text{A}$
8	1120 $\mu\text{A}$	1800 $\mu\text{A}$

Mechanical test setup

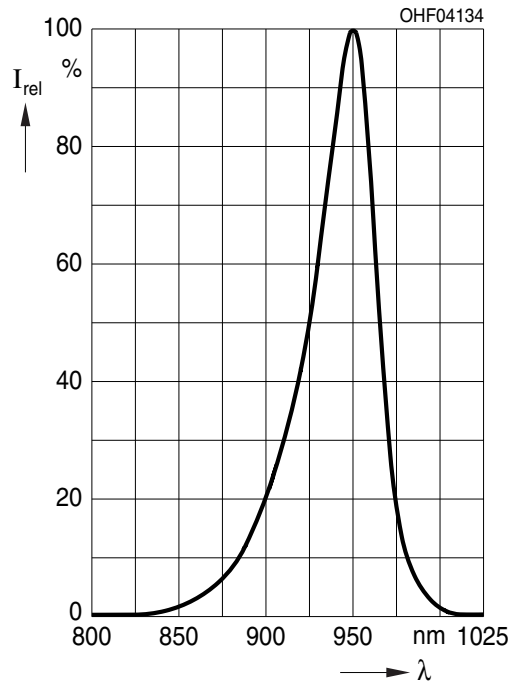


Test Circuit for Switching and Response Time



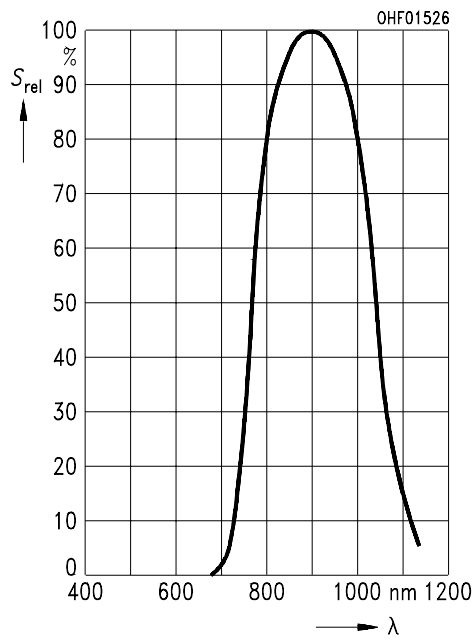
### Relative Spectral Emission <sup>1)</sup>

(typ)  $I_{rel} = f(\lambda)$ ,  $T_A = 25^\circ\text{C}$



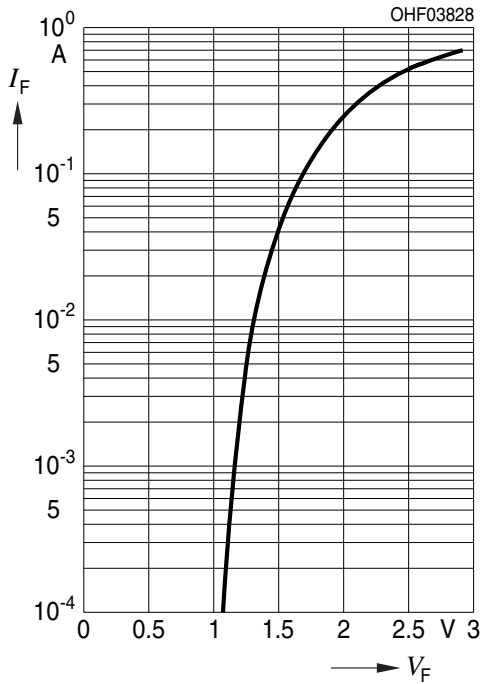
### Relative Spectral Sensitivity <sup>1)</sup>

$S_{rel} = f(\lambda)$ ,  $T_A = 25^\circ\text{C}$



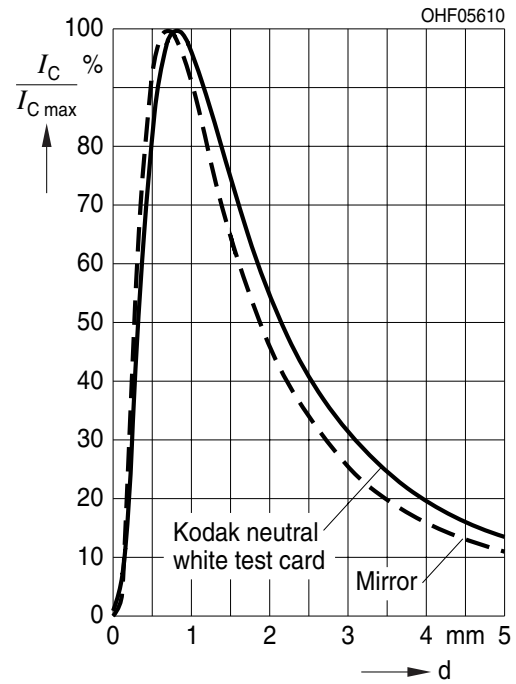
**Forward current** <sup>1)</sup>

$I_F = f(V_F)$  m single pulse,  $t_p = 100 \mu s$



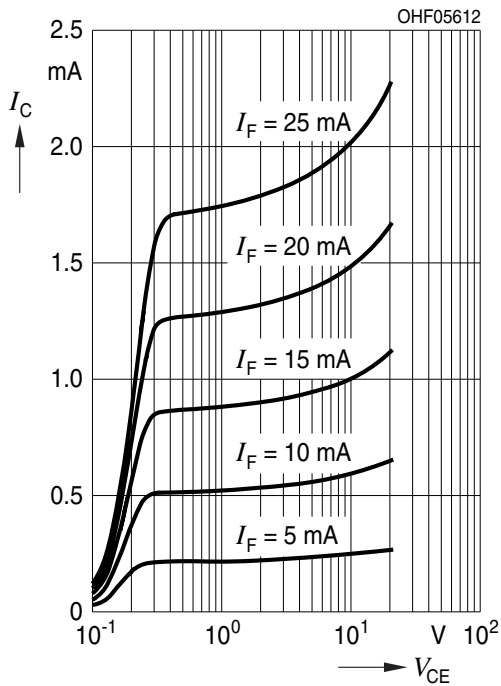
**Collector Current** <sup>1)</sup>

$I_C / I_{Cmax} = f(d)$ ,  $T_A = 25^\circ C$



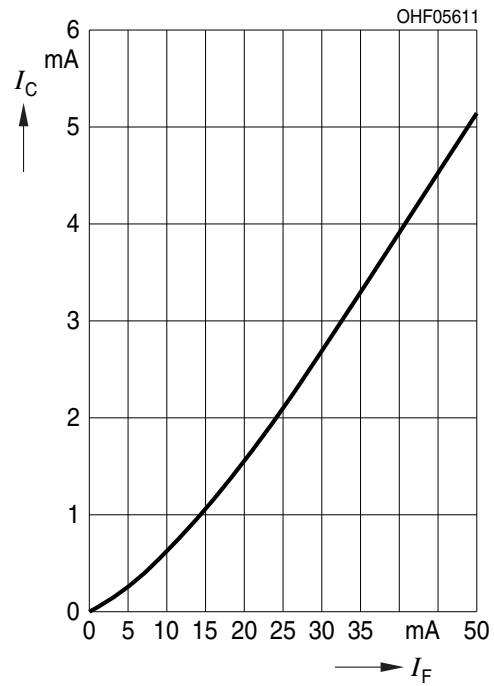
**Photocurrent** <sup>1)</sup>

$I_C = f(V_{CE})$ ,  $d = 1 \text{ mm}$ , 90% reflection,  $T_A = 25^\circ C$



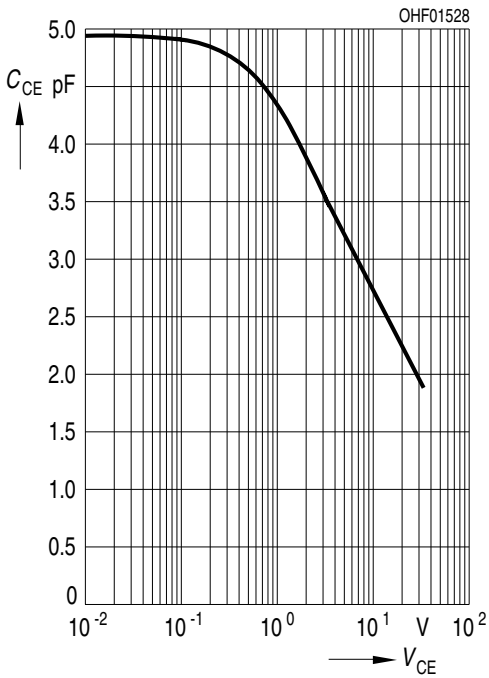
**Collector Current** <sup>1)</sup>

$I_C = f(I_F)$ ,  $d = 1 \text{ mm}$ , 90% reflection,  $T_A = 25^\circ C$



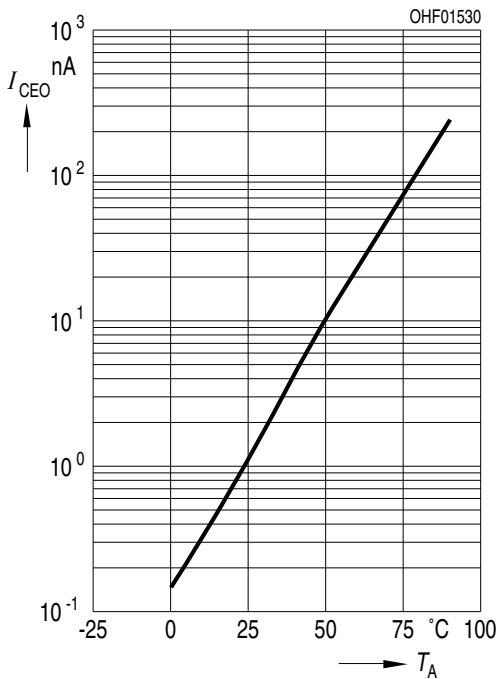
### Collector-Emitter Capacitance <sup>1)</sup>

$$C_{CE} = f(V_{CE}), f = 1 \text{ MHz}, E = 0, T_A = 25^\circ\text{C}$$



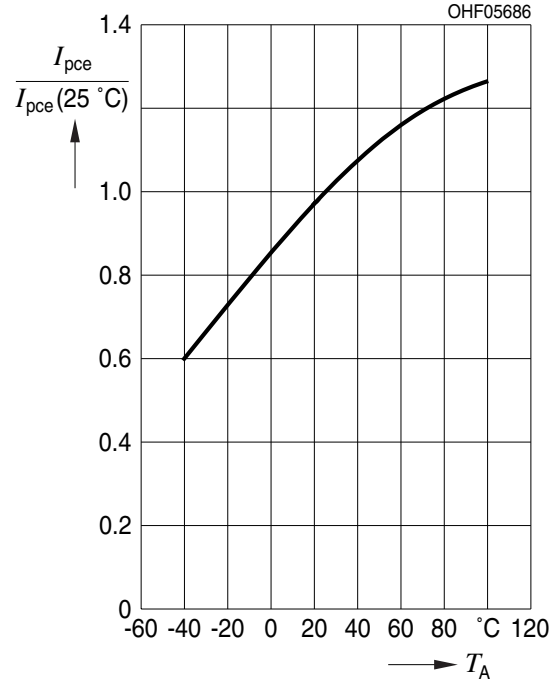
### Dark Current <sup>1)</sup>

$$I_{CEO} = f(T_A), V_{CE} = 20 \text{ V}, E = 0$$



### Photocurrent <sup>1)</sup>

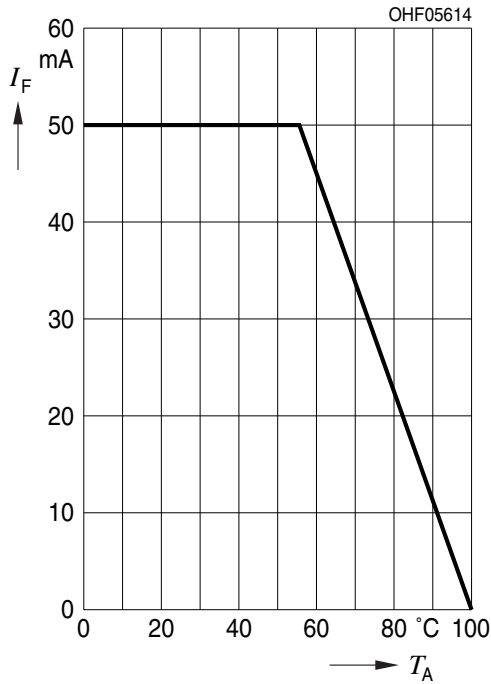
$$I_{PCE} / I_{PCE}(25^\circ\text{C}) = f(T_A), V_{CE} = 5 \text{ V}, I_f = 10 \text{ mA}$$





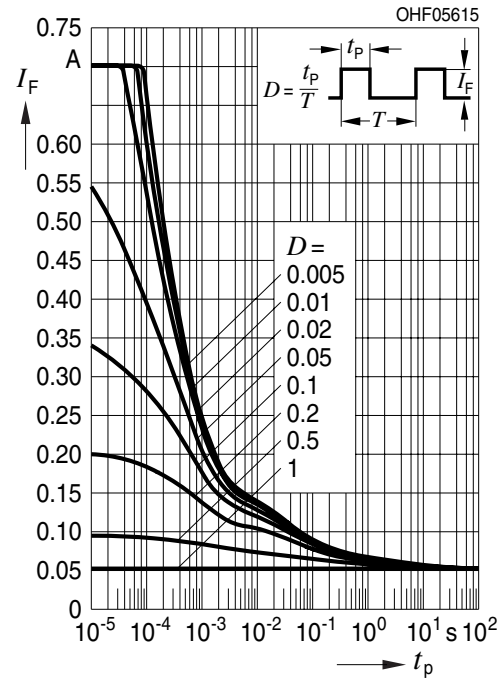
### Max. Permissible Forward Current

$I_F = f(T_A)$



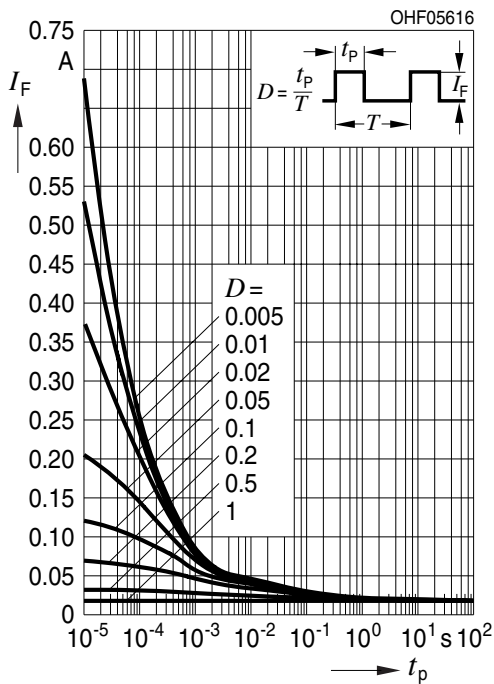
### Permissible Pulse Handling Capability

$I_F = f(t_p), T_A = 25^\circ\text{C}$ , duty cycle  $D =$  parameter



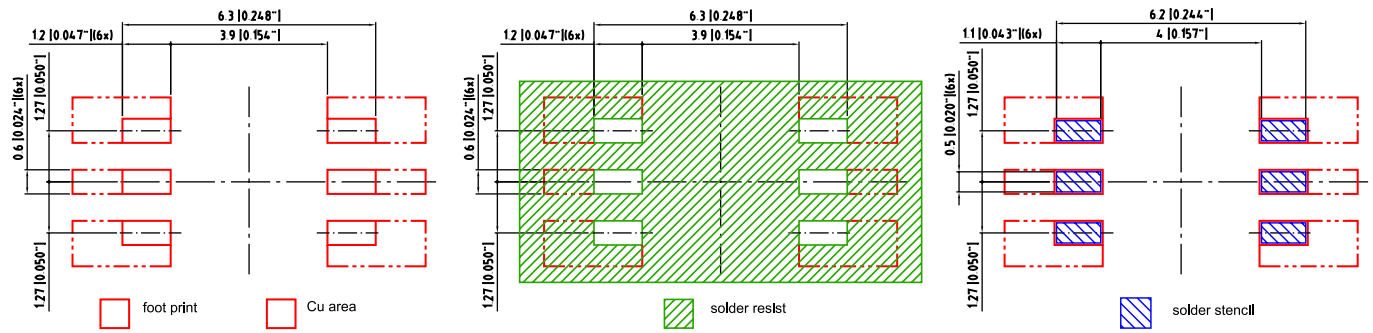
### Permissible Pulse Handling Capability

$I_F = f(t_p), T_A = 85^\circ\text{C}$ , duty cycle  $D =$  parameter

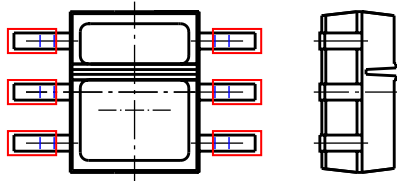




## Recommended Solder Pad <sup>2)</sup>



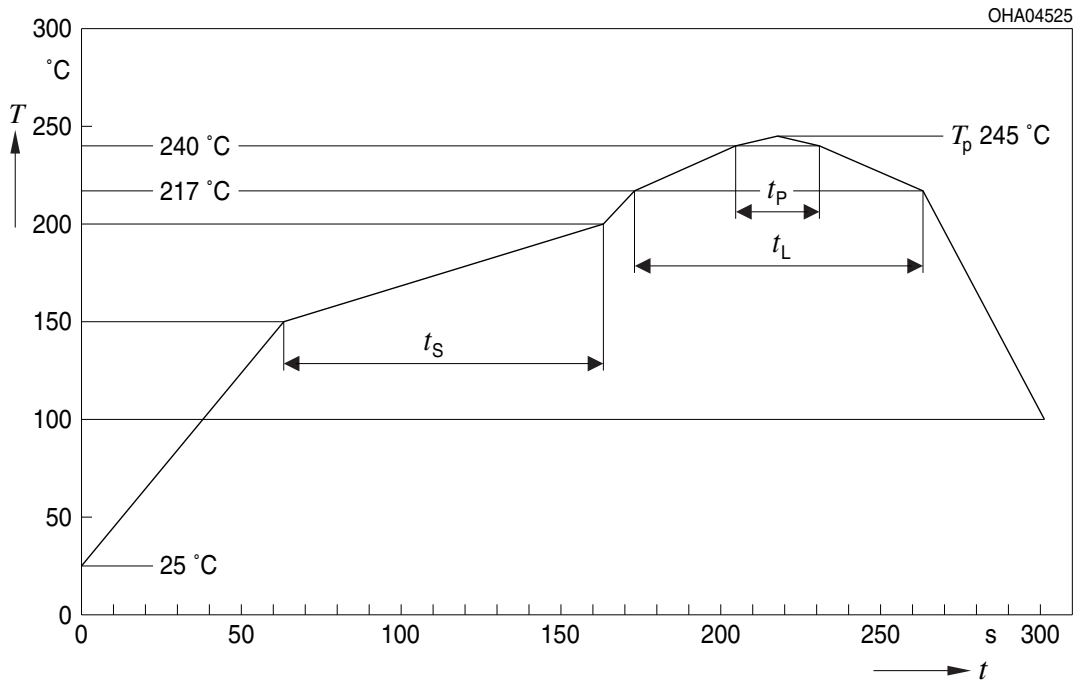
Component Location on Pad



E062.3010.158 -01

## Reflow Soldering Profile

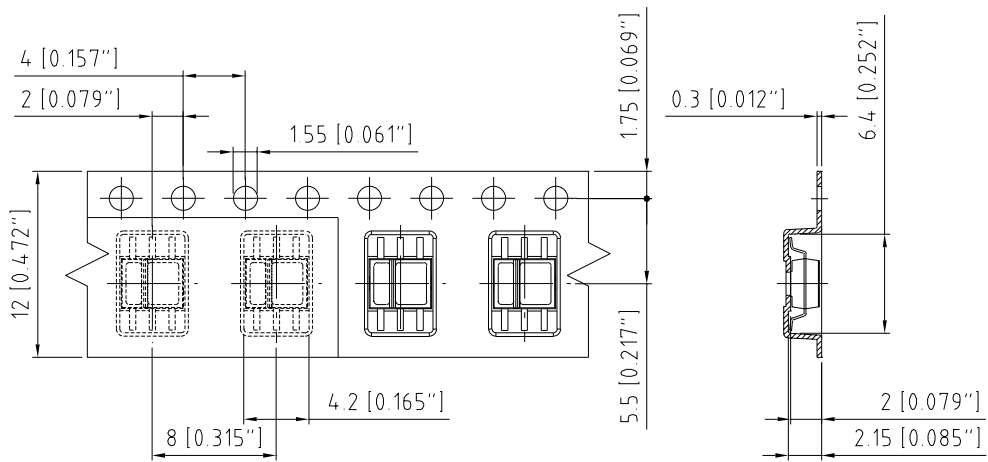
Product complies to MSL Level 4 acc. to JEDEC J-STD-020E



Profile Feature	Symbol	Pb-Free (SnAgCu) Assembly			Unit
		Minimum	Recommendation	Maximum	
Ramp-up rate to preheat <sup>*)</sup> 25 °C to 150 °C			2	3	K/s
Time $t_s$ $T_{Smin}$ to $T_{Smax}$	$t_s$	60	100	120	s
Ramp-up rate to peak <sup>*)</sup> $T_{Smax}$ to $T_p$			2	3	K/s
Liquidus temperature	$T_L$		217		°C
Time above liquidus temperature	$t_L$		80	100	s
Peak temperature	$T_p$		245	260	°C
Time within 5 °C of the specified peak temperature $T_p - 5$ K	$t_p$	10	20	30	s
Ramp-down rate* $T_p$ to 100 °C			3	6	K/s
Time 25 °C to $T_p$				480	s

All temperatures refer to the center of the package, measured on the top of the component  
 \*) slope calculation  $DT/Dt$ :  $Dt$  max. 5 s; fulfillment for the whole T-range

**Taping** <sup>2)</sup>



C63062-A3059-B10 -03

**Tape and Reel** <sup>3)</sup>



**Reel Dimensions**

A	W	N <sub>min</sub>	W <sub>1</sub>	W <sub>2max</sub>	Pieces per PU
180 mm	12 + 0.3 / - 0.1 mm	60 mm	12.4 + 2 mm	18.4 mm	1000

### Barcode-Product-Label (BPL)

**OSRAM Opto Semiconductors** LX XXXX BIN1: XX-XX-X-XXX-X

RoHS Compliant

(6P) BATCH NO: 1234567890

(1T) LOT NO: 1234567890 (9D) D/C: 1234

(X) PROD NO: 123456789 (Q) QTY: 9999 (G) GROUP: XX-XX-X-X

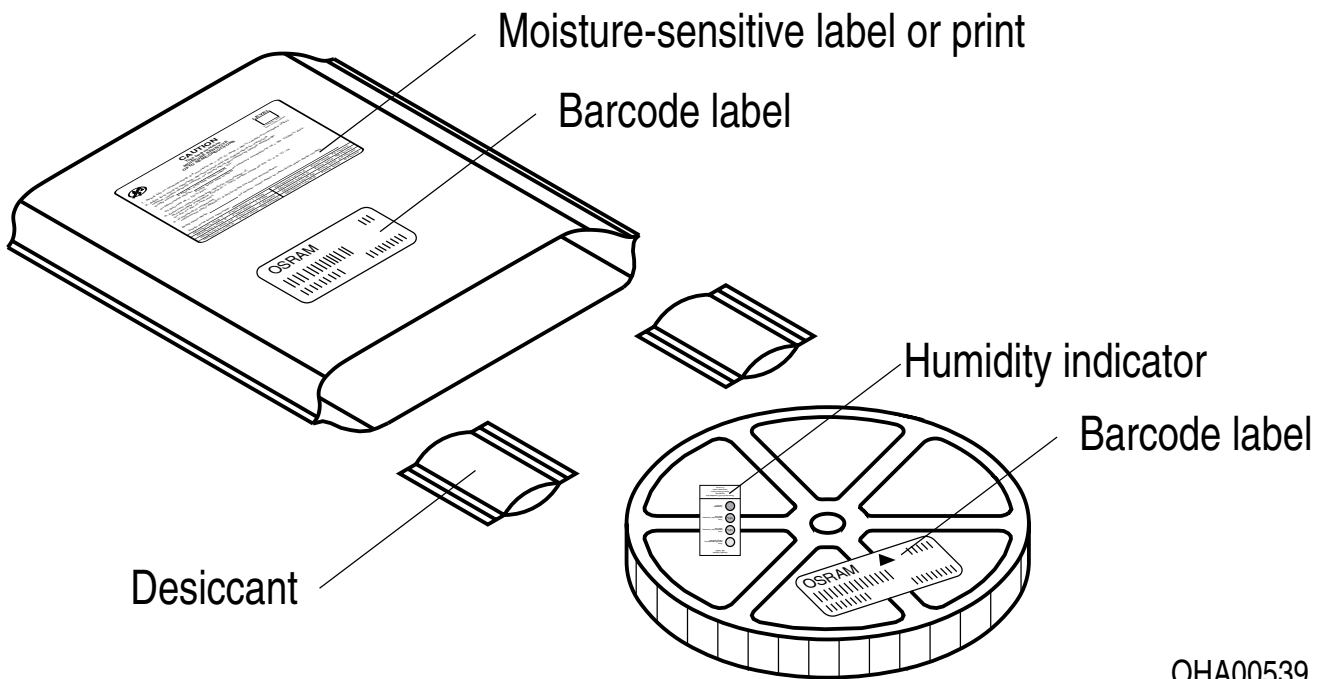
ML Temp ST  
X XXX °C X

Pack: RXX  
DEMY XXX  
X\_X123\_1234.1234 X

The diagram shows a rectangular label with rounded corners. It contains the OSRAM logo and company name at the top left. To the right are fields for 'LX XXXX' and 'BIN1: XX-XX-X-XXX-X'. Below this is 'RoHS Compliant'. The main body of the label features three rows of information, each with a corresponding barcode: '(6P) BATCH NO: 1234567890', '(1T) LOT NO: 1234567890 (9D) D/C: 1234', and '(X) PROD NO: 123456789 (Q) QTY: 9999 (G) GROUP: XX-XX-X-X'. To the right of the second row is a 'No moisture' symbol (a circle with a diagonal line and three droplets) and 'ML Temp ST X XXX °C X'. Below that is 'Pack: RXX', 'DEMY XXX', and 'X\_X123\_1234.1234 X'. A square QR code is located on the right side of the label.

OHA04563

### Dry Packing Process and Materials <sup>2)</sup>



OHA00539

## Disclaimer

### **Attention please!**

The information describes the type of component and shall not be considered as assured characteristics. Terms of delivery and rights to change design reserved. Due to technical requirements components may contain dangerous substances.

For information on the types in question please contact our Sales Organization.

If printed or downloaded, please find the latest version on the OSRAM OS website.

### **Packing**

Please use the recycling operators known to you. We can also help you – get in touch with your nearest sales office. By agreement we will take packing material back, if it is sorted. You must bear the costs of transport. For packing material that is returned to us unsorted or which we are not obliged to accept, we shall have to invoice you for any costs incurred.

### **Product and functional safety devices/applications or medical devices/applications**

OSRAM OS components are not developed, constructed or tested for the application as safety relevant component or for the application in medical devices.

OSRAM OS products are not qualified at module and system level for such application.

In case buyer – or customer supplied by buyer – considers using OSRAM OS components in product safety devices/applications or medical devices/applications, buyer and/or customer has to inform the local sales partner of OSRAM OS immediately and OSRAM OS and buyer and /or customer will analyze and coordinate the customer-specific request between OSRAM OS and buyer and/or customer.



## Glossary

- 1) **Typical Values:** Due to the special conditions of the manufacturing processes of semiconductor devices, the typical data or calculated correlations of technical parameters can only reflect statistical figures. These do not necessarily correspond to the actual parameters of each single product, which could differ from the typical data and calculated correlations or the typical characteristic line. If requested, e.g. because of technical improvements, these typ. data will be changed without any further notice.
- 2) **Tolerance of Measure:** Unless otherwise noted in drawing, tolerances are specified with  $\pm 0.1$  and dimensions are specified in mm.
- 3) **Tape and Reel:** All dimensions and tolerances are specified acc. IEC 60286-3 and specified in mm.
- 4) **Thermal resistance:** Mounting on PC-board with  $> 5 \text{ mm}^2$  pad size.
- 5)  $I_c$  as a function of the forward current of the emitting diode, the degree of reflection and the distance between reflector and component(d).

## Revision History

Version	Date	Change
1.6	2021-06-23	New Layout

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